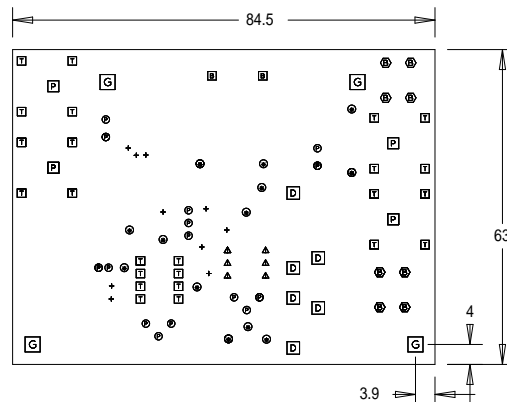



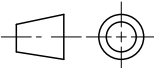
# SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE

MATERIAL	FR4 IMPROVED (low CTE)
BOARD THICKNESS	1.6mm /63mils
STACKUP	DF /2LAYERS
MINIMAL GAP	210um /8.0mils
MINIMAL SLIVER	210um /8.0mils
COPPER THICKNESS	35um(1oz)at START
FINISH THICKNESS	CHEMICAL NiAu
SOLDER MASK	GREEN TOP & BOT
SILKSCREEN	WHITE TOP
ALL BOARD ELECTRICALLY TESTED	
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK	



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILLIMETERS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
+	0.5	+0.0/-0.0	PLATED	10
⊙	0.8	+0.0/-0.0	PLATED	15
Δ	0.9	+0.0/-0.0	PLATED	6
⊙	1.0	+0.0/-0.0	PLATED	13
⊠	1.1	+0.0/-0.0	PLATED	2
⊠	1.4	+0.0/-0.0	PLATED	24
⊙	2.0	+0.0/-0.0	PLATED	8
⊠	2.2	+0.0/-0.0	PLATED	4
⊠	2.25	+0.05/-0.05	PLATED	6
G	3.0	+0.0/-0.0	NON-PLATED	4

1.0		44/2017	
indice		Description	
Date			
Controle par :		Autorise par :	
<div> ON semiconductor CM 84x EVB-A-TLS</div>		<div>Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE</div> <div></div>	
Subc.		Dessine: e B	
DYPE TECH		Echelle: 1/1	
Pages: 1/3			
Format: A3			